

## XP-002183614

AN - 1983-50724K [21]  
A - [001] 013 038 04- 075 080 140 154 180 213 214 215 216 231 262 273 293  
328 344 346 355 359 398 431 442 465 473 477 50& 532 533 534 536 537  
546 57- 575 596 623 627 628 681 689  
AP - JP19810164653 19811015  
CPY - KOBE  
DC - A21 A85 L03 P73  
FS - CPI;GMPI  
IC - B32B5/22 ; C08J5/24  
KS - 0004 0034 0037 0206 0231 1277 1357 1359 1389 1517 2020 2043 2064 2148  
2152 2172 2198 2317 2427 2436 2492 2493 2506 2509 2572 2575 2654 2725  
2740 3248  
MC - A05-C01 A11-B09A A12-B03 A12-E07A L03-H04E1  
PA - (KOBE ) SHIN KOBE ELECTRIC MACHINERY  
PN - JP58065649 A 19830419 DW198321 004pp  
- JP61043191B B 19860926 DW198643 000pp  
PR - JP19810164653 19811015  
XA - C1983-049316  
XIC - B32B-005/22 ; C08J-005/24  
XP - N1983-090898  
AB - J58065649 Mfr. comprises (a) impregnating paper with varnish  
consisting of (i) water-sol. phenol resin and (ii) chelating agents  
producing water-insol. chelates by reacting with silver ions; (b)  
heating the paper and drying it; (c) impregnating with another  
varnish; and (d) heating the paper and drying it.  
- Migration of silver atoms from one printed circuit to another is  
prevented. The chelating agent is e.g. EDTA or diphenylthiocarbazone.  
The amts. of chelating agents used are pref. 0.1-5 pts. wt. based on  
100 pts. wt. phenol resin. The varnish used in (c) is pref. lipophilic  
phenol resin.  
AW - PRINT CIRCUIT BOARD  
AKW - PRINT CIRCUIT BOARD  
IW - SILVER MIGRATION FREE PCB LAMINATE PREPARATION IMPREGNATE PAPER WATER  
SOLUBLE POLYPHENOL RESIN CHELATE AGENT REACT SILVER ION HEAT DRY  
IKW - SILVER MIGRATION FREE PCB LAMINATE PREPARATION IMPREGNATE PAPER WATER  
SOLUBLE POLYPHENOL RESIN CHELATE AGENT REACT SILVER ION HEAT DRY  
NC - 001  
OPD - 1981-10-15  
ORD - 1983-04-19  
PAW - (KOBE ) SHIN KOBE ELECTRIC MACHINERY  
TI - Silver migration-free PCB laminate prepn. - by impregnating paper with  
water-soluble phenol] resin and chelating agent reacting with silver  
ion, heating, drying etc.